

Type number	Package	Package description	Total product weight
74ALVCH16601DGG	SOT364-1	TSSOP56	218.47765 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935262546518	7	2	260	30 s	2	240	20 s	3	Bangkok, Thailand; Nijmegen, Netherlands	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Filler	Silver (Ag)	7440-22-4	0.01602	80.10000	0.00733
	Polymer	Resin system	Proprietary	0.00398	19.90000	0.00182
		subTotal		0.02000	100.00000	0.00915
Die	Doped silicon	Silicon (Si)	7440-21-3	3.15233	100.00000	1.44286
		subTotal		3.15233	100.00000	1.44286
Lead Frame Material	Copper alloy	Copper (Cu)	7440-50-8	55.64890	97.00000	25.47121
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	1.72110	3.00000	0.78777
		subTotal		57.37000	100.00000	26.25898
Mould Compound	Filler	Misc. Silica compounds (generic)	14808-60-7	136.29000	88.50000	62.38167
	Flame retardant	Non hazardous	Proprietary	4.62000	3.00000	2.11463
	Polymer	Epoxy resin system	Proprietary	13.09000	8.50000	5.99146
		subTotal		154.00000	100.00000	70.48776
Pre-Plating	Pure metal layer	Gold (Au)	7440-57-5	0.03150	1.00000	0.01442
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	3.05550	97.00000	1.39854
		Palladium (Pd)	7440-05-3	0.06300	2.00000	0.02884
		subTotal		3.15000	100.00000	1.44180
Wire	Pure metal	Gold (Au)	7440-57-5	0.77746	99.00000	0.35585
		Palladium (Pd)	7440-05-3	0.00785	1.00000	0.00359
		subTotal		0.78531	100.00000	0.35944

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, Nexperia does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. Nexperia may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.